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First Named Invent r	Datta, Madhav
Gr up Art Unit	2814
Examiner Name	Pham, Long

Sheet 1 of 1

Attorney Docket No: 884.522US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date if Appropriate
LP	US-3,663,184	05/16/1972	Wood, John R., et al.	29	195	01/23/1970
	US-4,290,079	09/15/1981	Carpenter, Charles, et al.	357	71	06/29/1979
	US-4,360,142	11/23/1982	Carpenter, Charles, et al.	228	123	05/08/1981
	US-4,505,029	03/19/1985	Owyang, King, et al.	29	589	07/08/1983
	US-5,648,686	07/15/1997	Hirano, Naohiko, et al.	257	778	07/26/1995
	US-5,736,456	04/07/1998	Akram, S.	438	614	07/17/1996
	US-5,773,359	06/30/1998	Mitchell, Douglas G., et al.	438	614	12/26/1995
	US-5,885,891	03/23/1999	Miyata, Masahiro, et al.	438	612	07/16/1997
	US-6,111,321	08/29/2000	Agarwala, Birendra N.	257	772	06/07/1995
	US-6,222,279	04/24/2001	Mis, Joseph D., et al.	257	779	04/20/1998
V	US-6,224,690	05/01/2001	Andricacos, Panayotis C., et al.	148	400	03/12/1996
	US-6,232,212	05/15/2001	Degani, Yinon, et al.	438	612	02/23/1999
	US-6,348,730	02/19/2002	Yi, Sang-Don, et al.	257	737	08/03/2000
	US-6,426,282	07/30/2002	Saigal, Dinesh, et al.	438	613	05/04/2000
	US-6,489,229	12/03/2002	Sheridan, Devin R., et al.	438	614	09/07/2001

FOREIGN PATENT DOCUMENTS

Examiner Initials	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
LP	JP-2001189334	07/10/2001	RI, Soton, et al.	H01L	21/60	

OTHER DOCUMENTS – NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
LP		"Chromium Copper Step Phasing", IBM Technical Disclosure Bulletin, (08/01/1977), pgs. 1005-1006	
LP		TUMMALA, RAO, et al., "Microelectronics Packaging Handbook, Semiconductor Packaging", Part 2, 2nd Edition, (1997), pgs. 132-139	

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Substitute Disclosure Statement Form (PTO-1449)
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Form 1449*	Atty. Docket No.: 884.522US1	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Madhav Datta et al.	
	Filing Date: Herewith	Group: Unknown

U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
LP	Annala, P., et al., "Electroplated Solder Alloys for Flip Chip Interconnections", <u>Physica Scripta</u> , T69, pp. 115-118, (1997)
I	Datta, M., et al., "Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections", <u>Journal of the Electrochemical Society</u> , 142 (11), 7 p., (Nov. 1995)
	Honma, S., et al., "Effectiveness of Thin-film Barrier Metals for Eutectic Solder Bumps", <u>Microelectronics International</u> , 14 (3), pp. 47-50, (Sept. 1997)
V	Liu, C.Y., et al., "Electron microscopy study of interfacial reaction between eutectic SnPb and Cu/Ni(V)/Al thin film metallization", <u>Journal of Applied Physics</u> , 86 (11), pp. 1-5, (Dec. 1999)

Examiner

Long Pham

Date Considered

6/21/05

*Substitute Disclosure Statement Form (PTO-1449)

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